



Application No.: 10/647,390
Attorney Docket No.: 80001-2796

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Substitute
Specification
Baker on
Examine
10/13/04

[0001]

Examine
20/13/04

[0002]

1. Field of the invention

[0003]

The invention relates to a method for fabricating a solid-state imaging device in which a metallic light shield film is formed to avoid light coming into an area other than a light receiving sensor.

[0004]

2. Description of Related Art

20 [0005]

Figs. 4A to 4D show steps of a conventional fabricating process of a solid-state imaging device. Conventionally, a solid-state imaging device is obtained by forming a metallic light-shield film 9 on the light receiving sensor 2 and the transfer electrode 7, as shown in Fig. 4A, after forming a light receiving sensor 2 that receives incoming light and saves it as electric charge and a transfer electrode 7, which transfers the saved electric charge on a surface layer of a wafer 1.

30 [0006]

In addition, as shown in Fig. 4B, an opening is